

# SN74AHCT1G04-Q1 Automotive Single 4.5-V To 5.5-V Inverter With TTL-compatible CMOS Inputs

## 1 Features

- Qualified for automotive applications
- ESD protection exceeds 1500 V per MIL-STD-883, method 3015; exceeds 200 V using machine model (C = 200 pF, R = 0)
- Operating range of 4.5 V to 5.5 V
- Max tpd of 7.5 ns at 5 V
- Low power consumption, 10-μA max ICC
- 8-mA output drive at 5 V
- Inputs are TTL-voltage compatible

## 2 Applications

- Hybrid, Electric, and Powertrain Systems
- Advanced Driver Assistance Systems (ADAS)
- Body Electronics and Lighting
- Infotainment and Cluster

## 3 Description

The SN74AHCT1G04-Q1 contains one gate. The device performs the Boolean function  $Y = \overline{A}$ .

### Package Information

PART NUMBER	PACKAGE <sup>1</sup>	PACKAGE SIZE <sup>2</sup>
SN74AHCT1G04-Q1	DCK (SOT-SC70, 5)	2.00 mm x 1.25 mm

1. For all available packages, see the orderable addendum at the end of the data sheet.
2. The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Schematic



## Table of Contents

<b>1 Features</b> .....	<b>1</b>	<b>7 Parameter Measurement Information</b> .....	<b>6</b>
<b>2 Applications</b> .....	<b>1</b>	<b>8 Detailed Description</b> .....	<b>7</b>
<b>3 Description</b> .....	<b>1</b>	8.1 Functional Block Diagram.....	<b>7</b>
<b>4 Revision History</b> .....	<b>2</b>	8.2 Device Functional Modes.....	<b>7</b>
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	<b>9 Device and Documentation Support</b> .....	<b>8</b>
<b>6 Specifications</b> .....	<b>4</b>	9.1 Documentation Support.....	<b>8</b>
6.1 Absolute Maximum Ratings.....	<b>4</b>	9.2 Receiving Notification of Documentation Updates.....	<b>8</b>
6.2 ESD Ratings.....	<b>4</b>	9.3 Support Resources.....	<b>8</b>
6.3 Recommended Operating Conditions.....	<b>4</b>	9.4 Trademarks.....	<b>8</b>
6.4 Thermal Information.....	<b>4</b>	9.5 Electrostatic Discharge Caution.....	<b>8</b>
6.5 Electrical Characteristics.....	<b>5</b>	9.6 Glossary.....	<b>8</b>
6.6 Switching Characteristics.....	<b>5</b>	<b>10 Mechanical, Packaging, and Orderable</b>	
6.7 Operating Characteristics.....	<b>5</b>	<b>Information</b> .....	<b>9</b>
6.8 Typical Characteristics.....	<b>5</b>		

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision B (January 2023) to Revision C (July 2023)</b>	<b>Page</b>
• Updated thermal values for DCK package from R $\theta$ JA = 252 to 293.4, all values in °C/W.....	<b>4</b>

<b>Changes from Revision A (June 2003) to Revision B (January 2023)</b>	<b>Page</b>
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	<b>1</b>

## 5 Pin Configuration and Functions

Figure 5-1. DCK Package Top View

NC – No internal connection

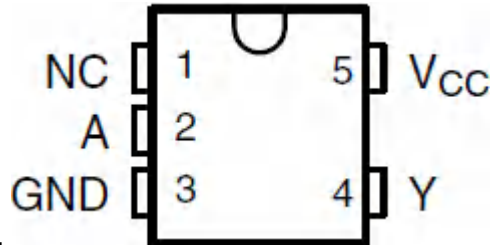


Figure 5-2.

Table 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	NC	—	No Connection
2	A	I	Input A
3	GND	—	Ground Pin
4	Y	O	Output Y
5	V <sub>CC</sub>	—	Power Pin

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	-0.5	7	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	7	V
V <sub>O</sub>	Output voltage range	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub>	±20	mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>	±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [Section 6.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±1500 V

- (1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		V
V <sub>IL</sub>	Low-level Input voltage		0.8	V
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		-8	mA
I <sub>OL</sub>	Low-level output current		8	mA
Δt/Δv	Input Transition rise or fall rate		20	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, [Implications of Slow or Floating CMOS Inputs](#).

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DCK (SC-70)	UNIT
		5 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	293.4	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

### 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			-40°C to +125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.5		4.4		V
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1	V
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.44	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			± 0.1		±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			1		10	μA
ΔI <sub>CC</sub> <sup>1</sup>	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10		10	pF

### 6.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see [load circuit and voltage wave forms](#))

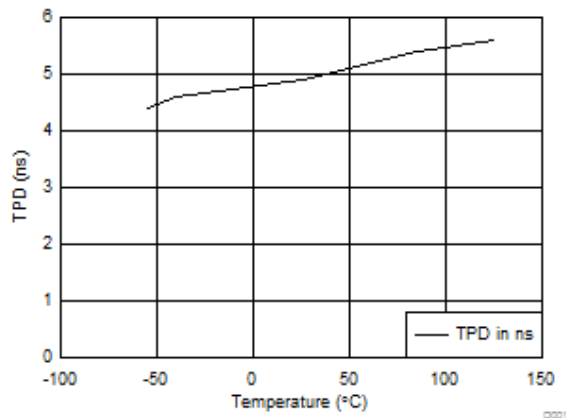
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 15 pF		4.7	6.7	1	7.5	ns
t <sub>PHL</sub>	A	Y	C <sub>L</sub> = 15 pF		4.7	6.7	1	7.5	
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 50 pF		5.5	7.7	1	8.5	ns
t <sub>PHL</sub>	A	Y	C <sub>L</sub> = 50 pF		5.5	7.7	1	8.5	

### 6.7 Operating Characteristics

V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

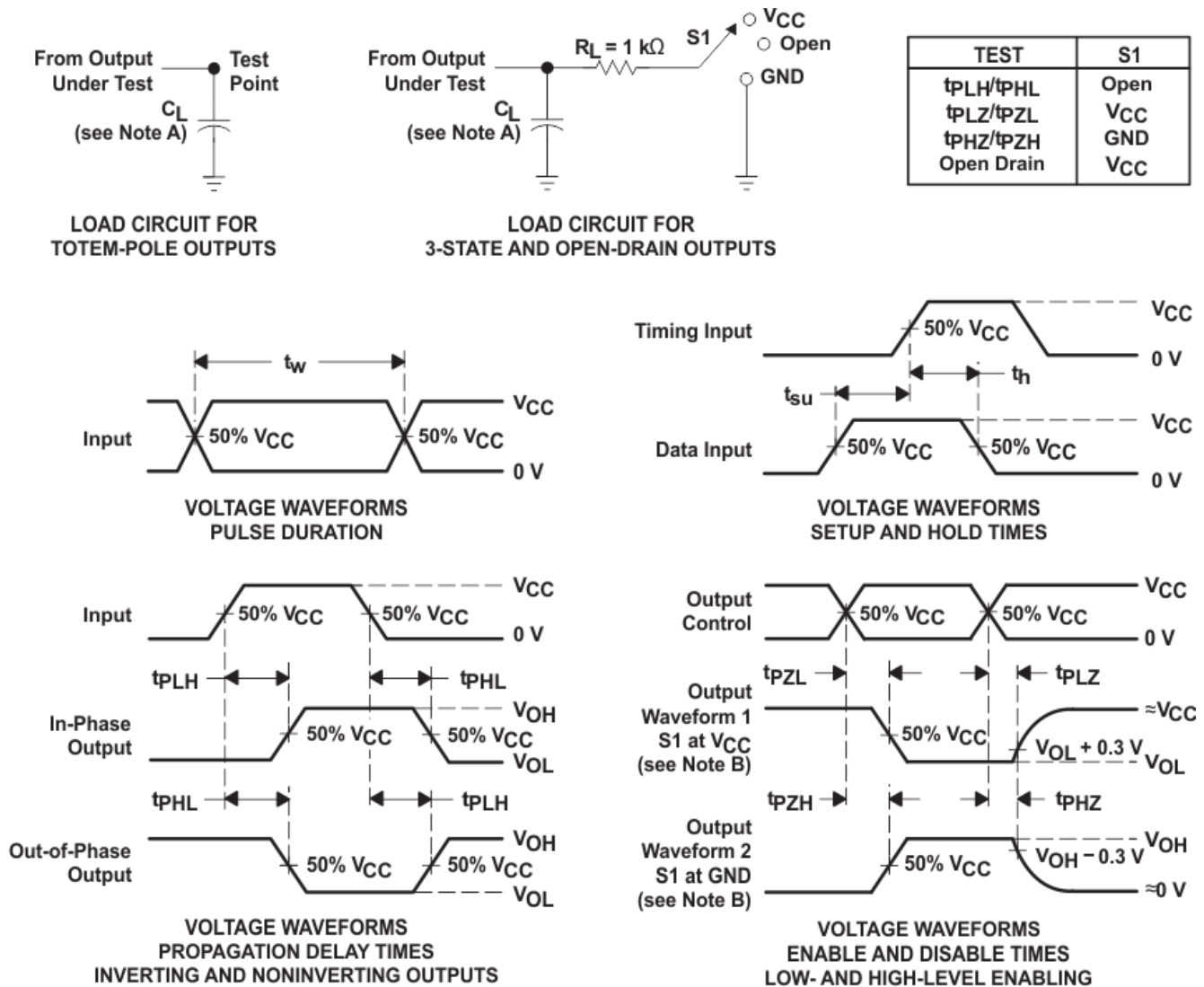
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	14	pF

### 6.8 Typical Characteristics



## 7 Parameter Measurement Information

### 7.1



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .  
 D. The outputs are measured one at a time, with one input transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

**Figure 7-1. Load Circuit and Voltage Waveforms**

## 8 Detailed Description

### 8.1 Functional Block Diagram



### 8.2 Device Functional Modes

**Table 8-1. Function Table**

INPUT	OUTPUT
A	Y
H	L
L	H

## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 9-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74AHCT1G04-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

#### [TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.



## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CAHCT1G04QDCKRG4Q1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BCS	<a href="#">Samples</a>
CAHCT1G04QDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BCS	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74AHCT1G04-Q1 :**

- Catalog : [SN74AHCT1G04](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAHCT1G04QDCKRQ1	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CAHCT1G04QDCKRQ1	SC70	DCK	5	3000	190.0	190.0	30.0

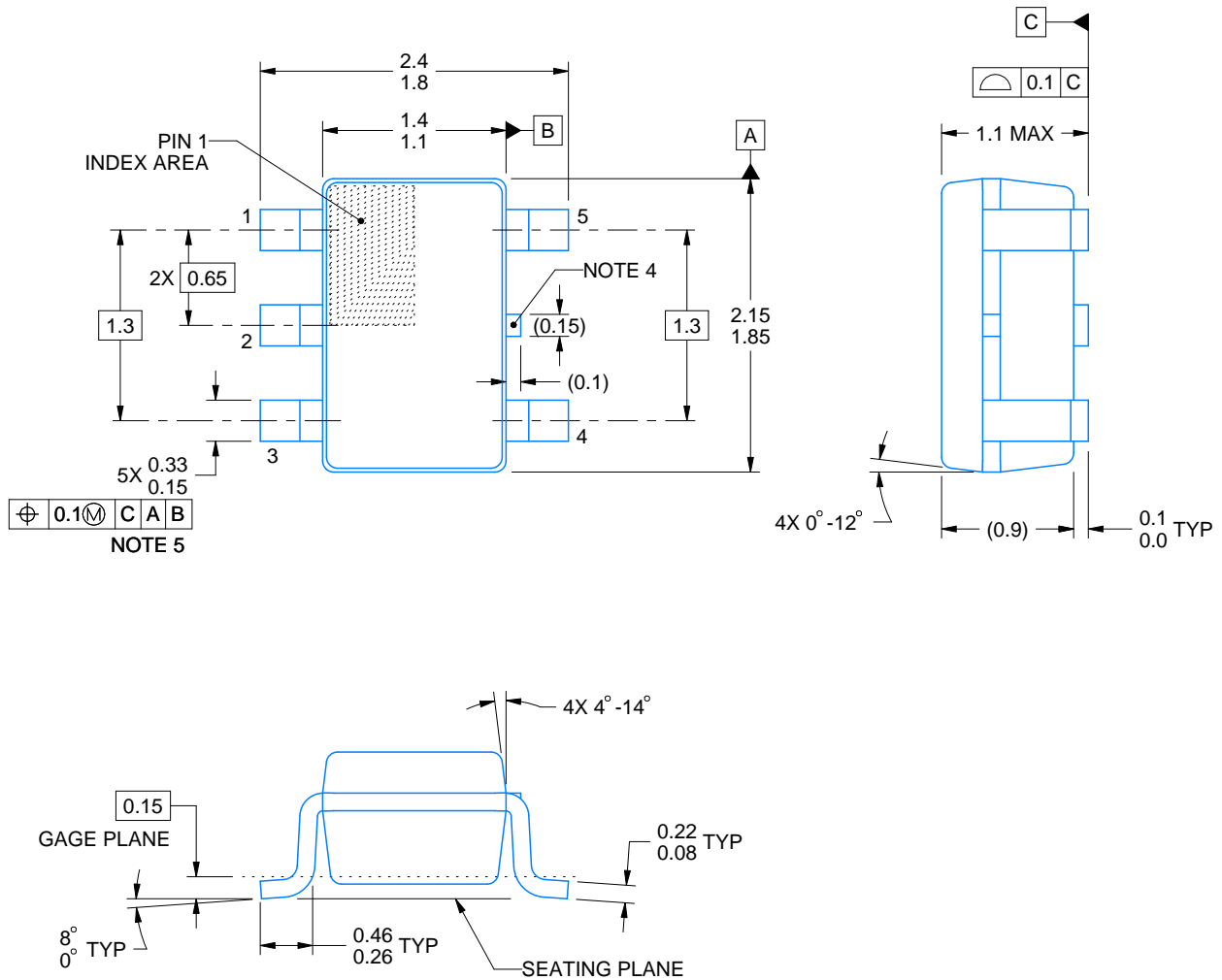
# DCK0005A



## PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214834/F 08/2024

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

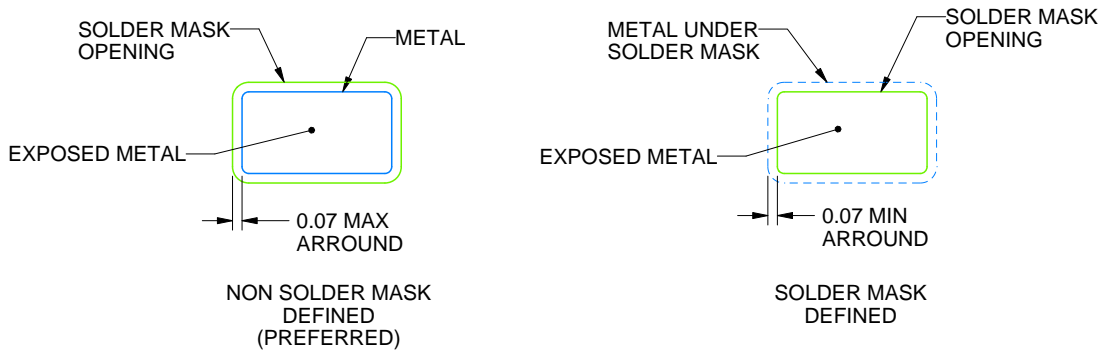
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

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NOTES: (continued)

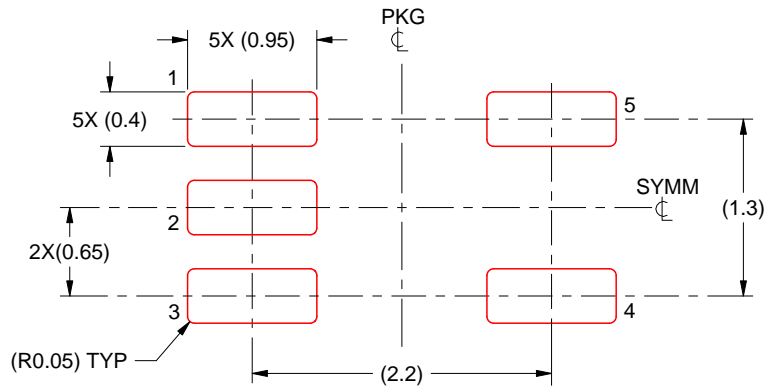
7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

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NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.



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